



12-16-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

) Art Unit: 2829

Hongyong ZHANG et al.

) Examiner: E. Pert

Serial No. 09/695,414

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Filed: October 25, 2000

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For: METHOD FOR FORMING
SEMICONDUCTOR DEVICE

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CERTIFICATE OF MAILING

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AMENDMENT

Honorable Commissioner of Patents

Washington, D.C. 20231

Sir:

In response to the Office Action dated July 23, 2002 please amend the above-
identified application as follows:

IN THE CLAIMS:

Please amend claims 2, 5, 8, 11, 14 and 17 as follows:

C1
2. (Amended) The method according to claim 1 wherein said metal is
selected from the group consisting of Ni, Pd, Pt, Cu, Ag, Au, In, Sn, and Sb.

C2
5. (Amended) The method according to claim 4 wherein said metal is
selected from the group consisting of Ni, Pd, Pt, Cu, Ag, Au, In, Sn, and Sb.

C3
8. (Amended) The method according to claim 7 wherein said metal is
selected from the group consisting of Ni, Pd, Pt, Cu, Ag, Au, In, Sn, and Sb.

C4
11. (Amended) The method according to claim 10 wherein said metal is
selected from the group consisting of Ni, Pd, Pt, Cu, Ag, Au, In, Sn, and Sb.

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C5
14. (Amended) The method according to claim 13 wherein said metal is selected from the group consisting of Ni, Pd, Pt, Cu, Ag, Au, In, Sn, and Sb.

C6
17. (Amended) The method according to claim 16 wherein said metal is selected from the group consisting of Ni, Pd, Pt, Cu, Ag, Au, In, Sn, and Sb.